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PLED

OPA2348AIDR-MS/OPA2348AIDGKR-MS

Product specification





GENERAL DESCRIPTION

The OPA2348AIDR-MS/OPA2348AIDGKR-MS is dual CMOS operational amplifier that uses the propriet ary auto-calibration technique to simultaneously provides very low offset voltage near-zero drift over time and temperature. These miniature, high-precision, low quiescent current amplifiers offer high-impedance inputs that have a common-mode range 200mV beyond the rails, and rail-to-rail output that swings within 50mV of the rails single or dual supplies as low as 2.1V(±1.35V) and up to 5.5V(±2.75V) can be used. These devices are optimized for low voltage, single supply operation.

The OPA2348AIDR-MS/OPA2348AIDGKR-MS offers excellent CMRR without the crossover associated with traditional complementary input stages. This design results in superior performance for driving anal og-to-digital converters (ADC) without degradation of differential linearity.

The OPA2348AIDR-MS/OPA2348AIDGKR-MS is available in the 8-pin and VSSOP packages.

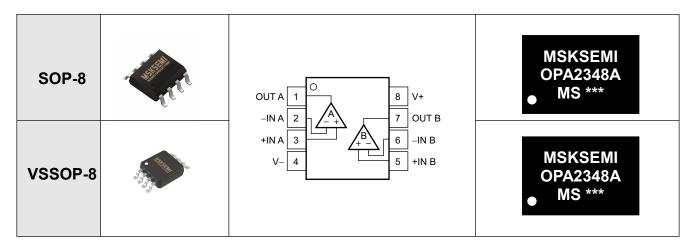
FEATURES

- VDD range:2.1Vto5.5V
- Low Offset Voltage:0.5mV (Typical)
- Low Drit:0.65µV/°C(Typical)
- Low Noise
- Quiescent Current:50µA(Total)
- Rail to Rail Input/Output
- MicroSize Packages:SOP8 and VSSOP8

APPLICATIONS

- Transducers
- Temperature Measurement
- Electronic Scales
- Medical instrumentation
- Handheld Test Equipment

Pin Description and Marking



PIN						
NAME	SOP-8	VSSOP-8	I/O	DESCRIPTION		
–IN A	2	2	ı	Inverting input, channel A		
–IN B	6	6	ı	Inverting input, channel B		
+IN A	3	3	ı	Noninverting input, channel A		
+IN B	5	5	ı	Noninverting input, channel B		
OUT A	1	1	0	Output, channel A		
OUT B	7	7	0	Output, channel B		
V-	4	4	_	Negative (lowest) power supply		
V+	8	8	_	Positive (highest) power supply		



SIMPLIFIED SCHEMATIC

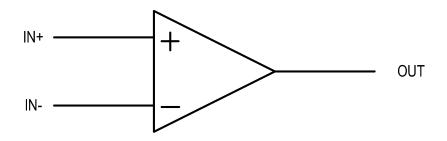


Figure 1. Simplified Schematic

ABSOLUTE MAXIMUM RATINGS

Thermal Resistance θ Jc	130°C/W
Supply Voltage	2.1to 5.5V
Signal Input Terminals Voltage	-0.1 to (V+)+0.1V
Operating Junction Temperature	150°C
Operating Temperature Range	40°Cto125°C
Storage Temperature	65°C to 150°C

ordering information

P/N	PKG	QTY
OPA2348AIDR-MS	SOP-8	2500
OPA2348AIDGKR-MS	VSSOP-8	3000



ELECTRICAL CHARACTERISTICS

(At $T_A = 25$ °C, $R_L=10k$ connected to $V_S/2$, and $V_{OUT}=V_S/2$, unless otherwise noted.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
Input Offset Voltage	V _S =±2.5V	-2	0.5	2	mV
Input Offset Voltage Drift	T _A = -55°C to 125°C		0.65		μV/°C
Power Supply Rejection Ratio	V _S =2.1V to 5.5V T _A = -55°C to 125°C	80	90		dB
Input Bias Current	T _A = 25°C		2		pА
Input Offset Current			1		pА
Common-mode Voltage Range		(V-)-0.1		(V+)+0.1	V
Common-mode Rejection Ratio	$(V-)-0.1 < V_{CM} < (V+)+0.1$ T _A = -55°C to 125°C	80	95		dB
Open Loop Voltage Gain	(V-)+100mV <v<sub>O<(V+)-10 0mV, R_L=10k T_A = -55°C to 125°C</v<sub>	80	100		dB
Gain-bandwidth product	C _L =120pF		1.5		MHz
Slew Rate	G=+1		1.2		V/µs
Specified Voltage Range		2.1		5.5	V
Quiescent Current (Total)	Io=0A		50		μA
Operating Temperature Range		-55		125	°C
Storage Temperature Range		-65		150	°C



TYPICAL PERFORMANCE CHARACTERISTICS

(At T_A = 25°C,V_S=5V, C_L=20pF, unless otherwise noted.)

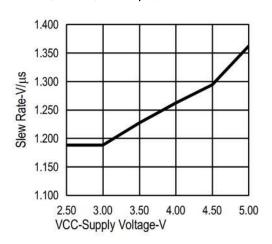


Figure 2. Slew Rate vs Supply Voltage

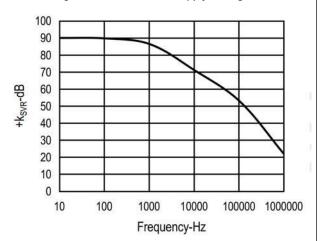


Figure 4. +ksvR vs Frequency

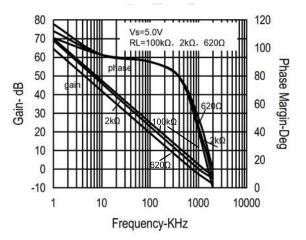


Figure 6. Frequency Response vs Resistive Load

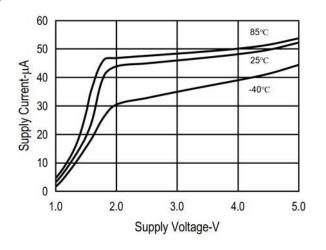


Figure 3. Supply Current vs Supply Voltage

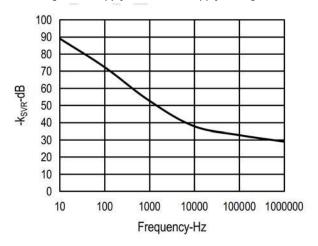


Figure 5. -ksvR vs Frequency

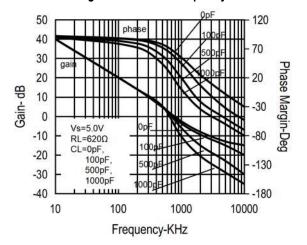


Figure 7. Frequency Response vs Capacitive Load



TYPICAL PERFORMANCE CHARACTERISTICS

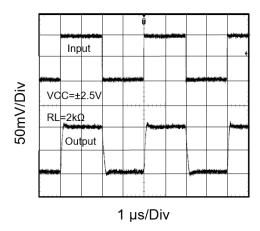


Figure 8. Noninverting Small-Signal Pulse Response

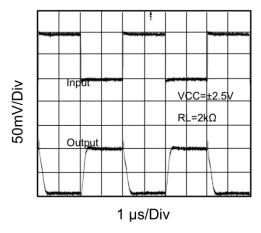


Figure 10. Inverting Small-Signal Pulse Response

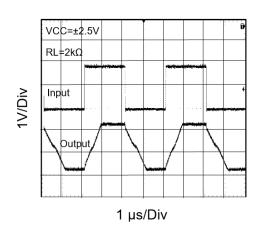


Figure 9. Noninverting Large-Signal Pulse Response

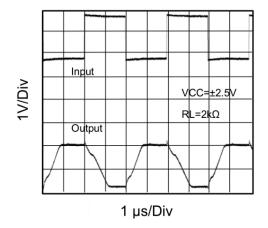


Figure 11. Inverting Large-Signal Pulse Response

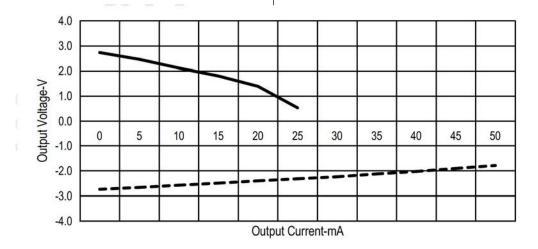


Figure 12. Output Voltage vs Output Current

OPA2348AIDR-MS/OPA2348AIDGKR-MS

FUNCTIONAL DESCRIPTION

Operating Voltage

The OPA2348AIDR-MS/OPA2348AIDGKR-MS device is fully specified and ensured for operation from 2.1V to 5.5V.In addition,many specifications apply from -55°C to 125°C. Parameters that vary significantly with operating voltages or temperature are shown in the Typical Characteristics graphs

Unity-Gain Bandwidth

The unity-gain bandwidth is the frequency up to which an amplifier with a unity gain may be operated without greatly distorting the signal. The OPA2348AIDR-MS/OPA2348AIDGKR-MSdevice has a 1.5-MHz unity-gain bandwidth.

Slew Rate

The slew rate is the rate at which an operational amplifier can change its output when there is a change on the input. The OPA2348AIDR-MS/OPA2348AIDGKR-MS devices have a $1.2\text{-V/}\mu$ s slew rate. The LMV358-MS is characterized to perform with this technique; the recommended resistor value is approximately 20 k.

Device Functional Modes

The OPA2348AIDR-MS/OPA2348AIDGKR-MS device has a single functional mode. The device is powered on as long as the power supply voltage is between 2.1V(±1.35V)and 5.5V(±2.75V).

APPLICATIONS INFORMATION

The OPA2348AIDR-MS/OPA2348AIDGKR-MS is a unity-gain stable, precision operational amplifier with very low offset voltage drift; these devices are also free from output phase reversal. Applications with noisy or high-impedance power supplies require decoupling capacitors close to the device power-supply pins. In most cases, 0.1 µF capacitors are adequate.

Typical Application

Figure 13 shows a simple circuit to convert a single-ended input into differential output. The OPA2348AIDR-MS/OPA2348AIDGKR-MS could be used to build this circuit. The circuit is composed of two amplifiers. One amplifier acts as a buffer and creates a voltage, Vour+. The second amplifier inverts the input and adds a reference voltage to generate Vour-. Both Vour+ and Vour-range from 0.5 to 2V. The difference, VDIFF, is the difference between VouT+ and VouT-.

Detailed Design Procedure

Linearity over the input range is key for good dc accuracy. The common mode input range and the output swing limitations determine the linearity. In general, an amplifier with rail-to-rail input and output swing is required. Bandwidth is a key concern for this design. Because OPA2348AIDR-MS/OPA2348AIDGKR-MS has a bandwidth of 1 MHz, this circuit will only be able to process signals with frequencies of less than 1 MHz.

Because the transfer function of Vour-is heavily reliant on resistors(R1,R2,R3,and R4),use resistors with low tolerances to maximize performance and minimize error. This design used resistors with resistance values of 36 k with tolerances measured to be within 2%. If the noise of the system is a key parameter, the user can select smaller resistance values (6 k or lower) to keep the overall system noise low. This ensures that the noise from the resistors is lower than the amplifier noise.

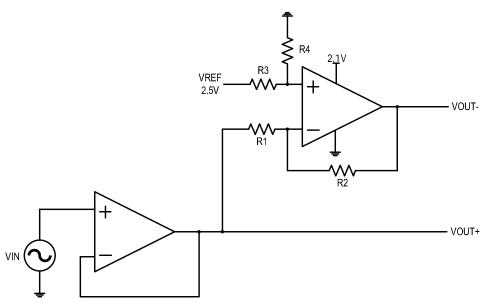
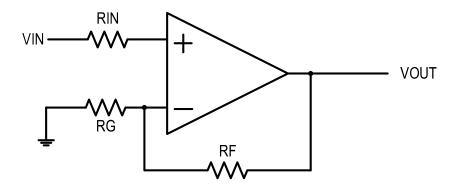


Figure 13. Schematic for Single-Ended Input to Differential Output Conversion

LAYOUT

Use good PCB layout practices for best operational performance of the device, including:

- Keep the length of input traces as short as possible.
- Run the input traces as far away from the supply lines as possible to reduce parasitic coupling.
- Place components close to device and to each other to reduce parasitic capacitance and parasitic errors.
- Use low-ESR, ceramic bypass capacitors to reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
- Grounding for analog and digital portions of circuitry separately to suppresse the noise.





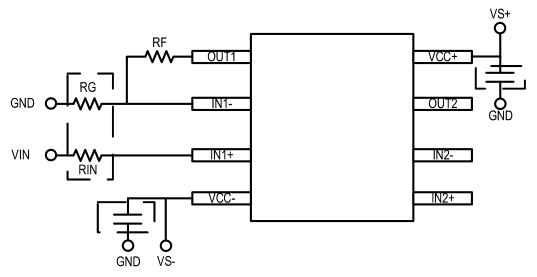
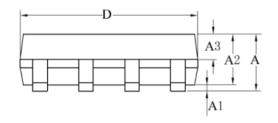


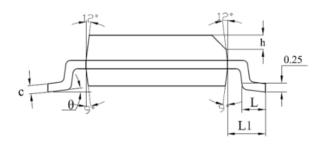
Figure 14. Operational Amplifier Schematic and Board Layout for Noninverting Configuration

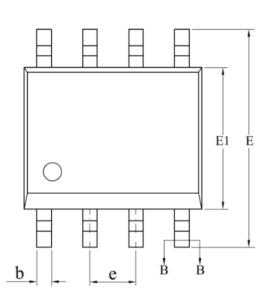


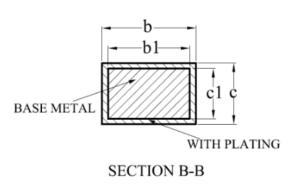
PACKAGE DESCRIPTION

SOP-8





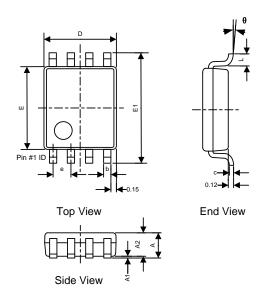




SYMBOL	millimeter				
STIVIDOL	min	nom	max		
A	-	-	1.75		
A1	0.10	-	0.23		
A2	1.30	1.40	1.50		
A3	0.60	0.65	0.70		
b	0.39	-	0.47		
b1	0.38	0.41	0.44		
С	0.20	-	0.24		
c1	0.19	0.20	0.21		
D	4.80	4.90	5.00		
E	5.80	6.00	6.20		
E1	3.80	3.90	4.00		
е	1.27BSC				
h	0.25	-	0.50		
L	0.50	-	0.80		
L1	1.05REF				
θ	0	-	8°		

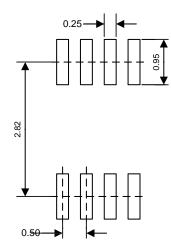


PACKAGE DESCRIPTION



DIMENSIONS							
Symbol	MILLIMETERS			INCHES			
	Min	Тур	Max	Min	Тур	Max	
A	0.60	0.75	0.90	0.023	0.029	0.035	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A2	0.60	0.70	0.80	0.023	0.027	0.031	
b	0.17	-	0.27	0.007	-	0.011	
с	0.08	1	0.23	0.003	-	0.009	
D	1.90	2.00	2.10	0.075	0.079	0.083	
Е	2.20	2.30	2.40	0.086	0.090	0.094	
E1	3.00	3.10	3.20	0.118	0.122	0.126	
e	0.50BSC			0.020BSC			
L	0.20	0.28	0.35	0.008	0.011	0.014	
θ	0°	3°	6°	0°	3°	6°	

Land Pattern



NOTES:

- 1. Compound dimension: 2.00×2.30;
- 2. Unit: mm;
- 3. General tolerance ± 0.05 mm unless otherwise specified;
- 4. The layout is just for reference.

OPA2348AIDR-MS/OPA2348AIDGKR-MS

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